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## ON Semiconductor®

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December 2014

## FQPF9P25YDTU

## P-Channel QFET® MOSFET

-250 V, -6 A, 620  $m\Omega$ 

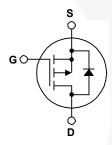
### **Description**

produced using Fairchild Semiconductor's proprietary planar stripe and DMOS technology. This advanced MOSFET technology has been especially tailored to reduce on-state resistance, and to provide superior switching performance and high avalanche energy strength. These devices are suitable for switched mode power supplies, audio amplifier, • 100% Avalanche Tested DC motor control, and variable switching power applications.

#### **Features**

- This P-Channel enhancement mode power MOSFET is -6 A, -250 V,  $R_{DS(on)}$  = 620 m $\Omega$  (Max.) @  $V_{GS}$  = -10 V,
  - Low Gate Charge (Typ. 29 nC)
  - Low Crss (Typ. 27 pF)





## Absolute Maximum Ratings T<sub>C</sub> = 25°C unless otherwise noted.

Symbol	Parameter		FQPF9P25YDTU	Unit
V <sub>DSS</sub>	Drain-Source Voltage		-250	V
I <sub>D</sub>	Drain Current - Continuous (T <sub>C</sub> = 25°C)		-6.0	Α
	- Continuous (T <sub>C</sub> = 100°C)		-3.9	Α
I <sub>DM</sub>	Drain Current - Pulsed	(Note 1)	-24	Α
V <sub>GSS</sub>	Gate-Source Voltage		± 30	V
E <sub>AS</sub>	Single Pulsed Avalanche Energy	(Note 2)	650	mJ
I <sub>AR</sub>	Avalanche Current	(Note 1)	-6.0	Α
E <sub>AR</sub>	Repetitive Avalanche Energy	(Note 1)	5.0	mJ
dv/dt	Peak Diode Recovery dv/dt	(Note 3)	-5.5	V/ns
$P_{D}$	Power Dissipation (T <sub>C</sub> = 25°C)		50	W
	- Derate above 25°C		0.4	W/°C
T <sub>J</sub> , T <sub>STG</sub>	Operating and Storage Temperature Range		-55 to +150	°C
T <sub>L</sub>	Maximum lead temperature for soldering, 1/8" from case for 5 seconds.		300	°C

#### **Thermal Characteristics**

Symbol	Parameter	FQPF9P25YDTU	Unit
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case, Max.	2.5	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient, Max.	62.5	°C/W

#### Package Marking and Ordering Information **Package** Packing Method **Part Number Top Mark** Reel Size **Tape Width** Quantity TO-220F FQPF9P25YDTU FQPF9P25 Tube N/A N/A 50 units (Y-formed) **Electrical Characteristics** T<sub>C</sub> = 25°C unless otherwise noted. Symbol **Parameter Test Conditions** Min. Max. Unit Тур. **Off Characteristics** $BV_{DSS}$ Drain-Source Breakdown Voltage $V_{GS} = 0 \text{ V}, I_D = -250 \mu\text{A}$ -250 ٧ $\Delta BV_{DSS}$ Breakdown Voltage Temperature $I_D = -250 \,\mu\text{A}$ , Referenced to 25°C -0.2 V/°C Coefficient $/\Delta T_J$ $V_{DS} = -250 \text{ V}, V_{GS} = 0 \text{ V}$ -1 $I_{DSS}$ μΑ Zero Gate Voltage Drain Current $V_{DS}$ = -200 V, $T_{C}$ = 125°C -----10 μΑ Gate-Body Leakage Current, Forward $V_{GS}$ = -30 V, $V_{DS}$ = 0 V -100 nΑ $I_{GSSF}$ Gate-Body Leakage Current, Reverse $V_{GS}$ = 30 V, $V_{DS}$ = 0 V 100 nΑ $I_{GSSR}$ On Characteristics $V_{DS} = V_{GS}, I_{D} = -250 \mu A$ ٧ V<sub>GS(th)</sub> Gate Threshold Voltage -3.0 -5.0 --Static Drain-Source R<sub>DS(on)</sub> $V_{GS} = -10 \text{ V}, I_D = -3.0 \text{ A}$ 0.48 0.62 Ω On-Resistance $V_{DS} = -40 \text{ V}, I_{D} = -3.0 \text{ A}$ Forward Transconductance g<sub>FS</sub> 4.8 --S **Dynamic Characteristics** Input Capacitance 910 1180 Ciss pF $V_{DS} = -25 \text{ V}, V_{GS} = 0 \text{ V},$ --Coss **Output Capacitance** 170 220 pF f = 1.0 MHz $C_{rss}$ Reverse Transfer Capacitance 27 35 pF **Switching Characteristics** Turn-On Delay Time 20 50 $t_{d(on)}$ ns $V_{DD} = -125 \text{ V}, I_{D} = -9.4 \text{ A},$ Turn-On Rise Time 150 310 $R_G = 25 \Omega$ Turn-Off Delay Time 45 100 $t_{d(off)}$ -ns (Note 4) $t_f$ Turn-Off Fall Time 65 140 ns $Q_g$ **Total Gate Charge** 29 38 $V_{DS} = -200 \text{ V}, I_D = -9.4 \text{ A},$ nC $Q_{gs}$ Gate-Source Charge 7.6 -nC $V_{GS} = -10 \text{ V}$ $Q_{qd}$ Gate-Drain Charge (Note 4) 14 nC **Drain-Source Diode Characteristics and Maximum Ratings** Maximum Continuous Drain-Source Diode Forward Current -6.0 Α Maximum Pulsed Drain-Source Diode Forward Current -24 $I_{SM}$ --Α $\overline{V}_{SD}$ Drain-Source Diode Forward Voltage $V_{GS} = 0 \text{ V}, I_{S} = -6.0 \text{ A}$ ---5.0 ٧ $t_{rr}$ Reverse Recovery Time $V_{GS} = 0 \text{ V}, I_{S} = -9.4 \text{ A},$ 190 ns

## Q<sub>rr</sub> Notes

- 1. Repetitive rating : pulse-width limited by maximum junction temperature.
- 2. L = 28.9 mH, I $_{AS}$  = -6.0 A, V $_{DD}$  = -50 V, R $_{G}$  = 25  $\Omega$ , starting T $_{J}$  = 25°C.
- 3. I  $_{SD} \leq$  -9.4 A, di/dt  $\leq$  300 A/µs , V  $_{DD} \leq$  BV  $_{DSS_s}$  starting T  $_J$  = 25°C.

Reverse Recovery Charge

4. Essentially independent of operating temperature.

μС

1.45

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 $dI_F / dt = 100 A/\mu s$ 

## **Typical Characteristics**

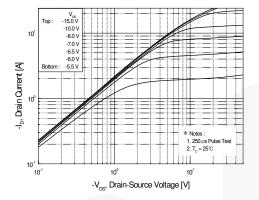


Figure 1. On-Region Characteristics

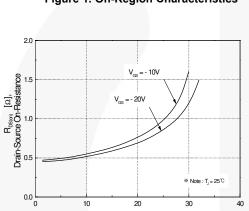


Figure 3. On-Resistance Variation vs. **Drain Current and Gate Voltage** 

-I<sub>D</sub> , Drain Current [A]

30

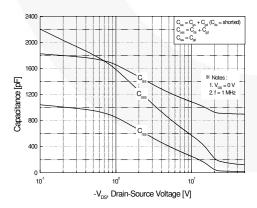


Figure 5. Capacitance Characteristics

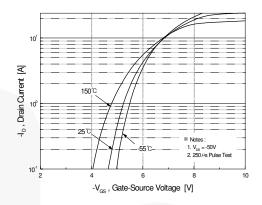


Figure 2. Transfer Characteristics

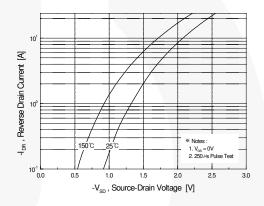


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

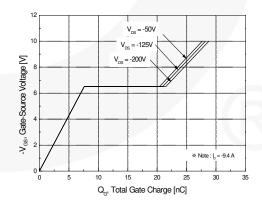
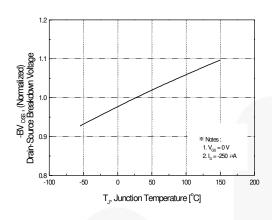


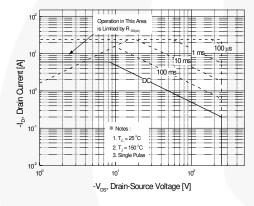
Figure 6. Gate Charge Characteristics



Typical Characteristics (Continued)

Figure 7. Breakdown Voltage Variation vs. Temperature

Figure 8. On-Resistance Variation vs. Temperature



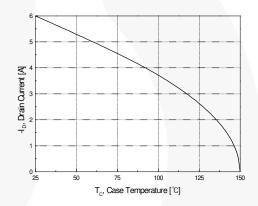


Figure 9. Maximum Safe Operating Area

Figure 10. Maximum Drain Current vs. Case Temperature

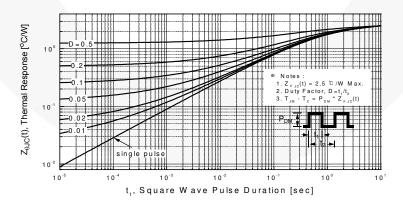


Figure 11. Transient Thermal Response Curve

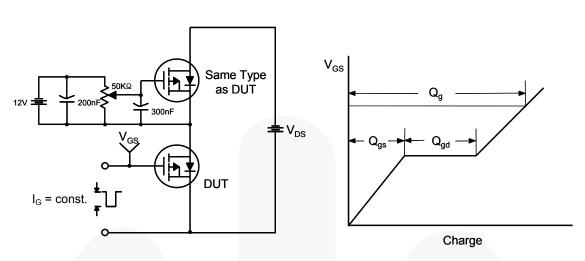


Figure 12. Gate Charge Test Circuit & Waveform

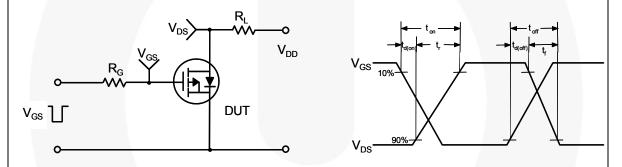


Figure 13. Resistive Switching Test Circuit & Waveforms

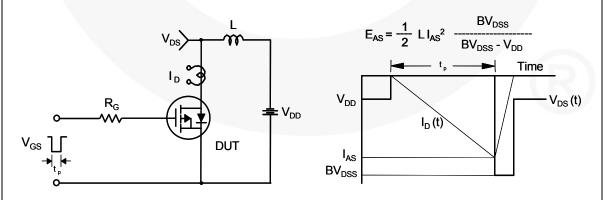
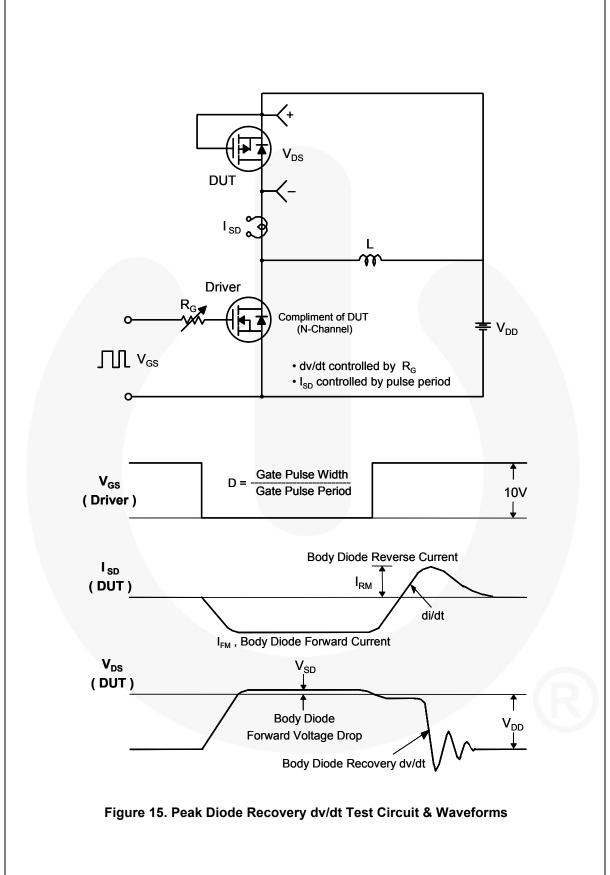
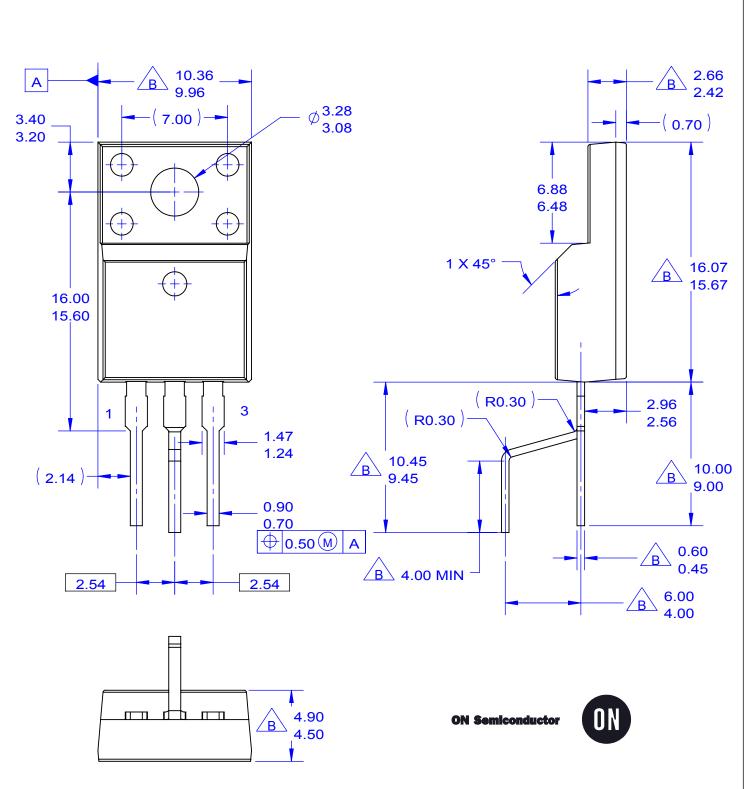


Figure 14. Unclamped Inductive Switching Test Circuit & Waveforms





#### NOTES:

- A. EXCEPT WHERE NOTED CONFORMS TO
- EIAJ SC91A.

  B DOES NOT COMPLY EIAJ STD. VALUE.
- C. ALL DIMENSIONS ARE IN MILLIMETERS.
- D. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH AND TIE BAR PROTRUSIONS.
- E. DIMENSION AND TOLERANCE AS PER ASME Y14.5-1994.
- F. DRAWING FILE NAME: TO220Q03REV2

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